

# MULTI-INNO TECHNOLOGY CO., LTD.

# **LCD MODULE SPECIFICATION**

# Model : MI12864AM-G

		Revis	sion	1.1
		Engi	neering	
		Date		
		Our 1	Reference	
Idrogg		Poom 101 Vin HooFong Duilding N	188 Shannan 1	Pood
ldress 1	:	Room 10J,Xin HaoFang Building, No Nanshan Drstrict, ShenZhen,China. (86-755)2643 9937	o.188 Shennan I	Road,
ldress I x	: : :	Room 10J,Xin HaoFang Building, N Nanshan Drstrict, ShenZhen,China. (86-755)2643 9937 (86-755)8613 4241	o.188 Shennan I	Road,
dress ‹ ıail	: : :	Room 10J,Xin HaoFang Building, Nanshan Drstrict, ShenZhen,China. (86-755)2643 9937 (86-755)8613 4241 sales@multi-inno.com	o.188 Shennan I	Road,



# History of Version

Date	Ver.	Edi.	Description	Page	Design by
03/15/2010	1.0	001	New Drawing.		
04/23/2010	1.1	002	New Sample. Modify 1.5 Optical Characteristics.	- 6	



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### **1. SPECIFICATIONS**

### 1.1 Features

Item	Standard Value		
Display Type	128 * 64 Dots		
LCD Type	FSTN, Positive, Transflective		
Driver Condition	LCD Module : 1/65 Duty, 1/9 Bias		
Viewing Direction	6 O'clock		
Backlight Type	LED (White)		
Weight	11 g		
Interface	Support 8 bits Parallel interface for 8080 or 6800 series MPU & Serial (4-Line SPI) interface		
Controller / Driver IC	Sitronix ST7567-G4		

# 1.2 Mechanical Specifications

Item	Standard Value	
Outline Dimension	55.2 (W) * 39.8 (L) * 5.0 (H)	mm
Viewing Area	45.2 (W) * 27.0 (L)	mm
Active Area	40.95 (W) * 24.31 (L)	mm
Dot Size	0.31 (W) * 0.37 (H)	mm
Dot Pitch	0.32 (W) * 0.38 (H)	mm

Note : For detailed information please refer to LCM drawing

# **1.3 Absolute Maximum Ratings**

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	VDD	-	-0.3	+3.6	V
LCD Power Supply Voltage	VLCD	V0-XV0	-0.3	+16	V
LCD Power Driving Voltage	VG, VM	-	-0.3	VDD	V
Operating Temperature	T <sub>OP</sub>	-	-20	+70	°C
Storage Temperature	T <sub>ST</sub>	-	-30	+80	°C
Storage Humidity	$H_{D}$	Ta < 40 °C	20	90	%RH



# **1.4 DC Electrical Characteristics**

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	VDD	VDD -		3.0	3.3	V
"H" Input Voltage	V <sub>IH</sub>	-	0.7*VDD	-	VDD	V
"L" Input Voltage	V <sub>IL</sub>	-	VSS	-	0.3*VDD	V
"H" Output Voltage	V <sub>он</sub>	IOUT=1mA, VDD=3.0V	0.8*VDD	I	VDD	V
"L" Output Voltage	V <sub>OL</sub>	IOUT=-1mA, VDD=3.0V	VSS	-	0.2*VDD	V
	IDD	VDD= 3.0V; Voe= 9.8V; Pattern= Full display	-	0.3	-	
Supply Current		VDD= 3.0V; Vo <sub>P</sub> = 9.8V; Pattern= Horizontal line *1	-	0.4	0.6	mA
		-20°C	9.7	10.0	10.3	
LCM Driver Voltage	Vop*2	+25°C	9.5	9.8	10.1	V
		+70°C	8.6	8.9	9.2	

Note : \*1. The Maximum current display. \*2. The Vop test point is V0 – XV0.



# **1.5 Optical Characteristics**

		LCD Panel:	<u>1/65 Dut</u>	<u>y, 1/9 Bia</u>	as, VLCL	) = 9.8V,	la = 25°C	
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit	Reference	
Response Time	Rise	tr		-	85	128	me	Note 2
Response nine	Fall	tf		-	215	323	1115	NOLE 2
	Тор	θ <b>Y</b> +	CR <u>&gt;</u> 2.0,	-	40	-		
\ <i>/</i>	Bottom	θ <b>Υ-</b>	$\varnothing$ = 270°	-	40	-		Notes 1
Viewing angle range	Left	θ <b>X-</b>		-	40	-		
	Right	⊖X+		_	40	-		
Contrast Ratio		CR	$\theta = 0^{\circ},$ $\varnothing = 270^{\circ}$	-	5	-	-	Note 3
Average Brightness (With B/L)		IV		30	50	-	cd/m <sup>2</sup>	-
CIE Color Coordinate (With B/L)		Х	IF=80mA	0.26	0.31	0.36	-	
		Y		0.29	0.34	0.39	-	Note 4
Uniformity	∆B	-	80	-	-	%		

Note 4:

1 : △B=B(min) / B(max)\*100%

2 : Measurement Condition for Optical Characteristics:

- a : Environment: 25°C ±5°C / 60±20%R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.
- b : Measurement Distance: 500 ± 50 mm  $\rightarrow$  ( $\theta$ = 0°)
- c : Equipment: TOPCON BM-7 fast , (field 0.2°) , after 10 minutes operation.
- d : The uncertainty of the C.I.E coordinate measurement  $\pm 0.01$  , Average Brightness  $\pm 4\%$





Colorimeter=BM-7 fast



















# 1.6 Backlight Characteristics

### Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Peak Forward current	IF		_	120	mA
Power dissipation	Pd	<b>Ta=25</b> ℃	_	0.6	W
Reverse Voltage	VR		_	10	V

### Electrical / Optical Characteristics

						<b>Га =25</b> ℃
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF=80mA	-	4.2	5	V
Reverse Current	IR	VR= 10V	-	-	0.2	mA
Average Brightness (Without LCD)	IV		200	300	-	cd/m <sup>2</sup>
CIE Color Coordinate	Х	IF=80mA	0.255	0.297	0.340	-
(Without LCD)	Y		0.265	0.307	0.35	-
Uniformity	∆В		80	-	-	%
Color			White			

Internal Circuit Diagram:





# 2. MODULE STRUCTURE

### 2.1 Counter Drawing

### 2.1.1 LCM Mechanical Diagram

\* See Appendix

### 2.1.2 Block Diagram





# 2.2 Interface Pin Description

Pin No.	Symbol	Function				
1	/CS1	Chip select signal, Active "L".				
2	/RES	Reset input pin.				
		It determines whether the access is related to data or command.				
3	A0	A0= "H" : display data.				
		A0=" L" : control data.				
4	/WR	Write signal input, Active "L".				
5	/RD	Read signal input, Active "L".				
6	D0	8-bit bi-directional data bus.				
7	D1	8-bit bi-directional data bus.				
8	D2	8-bit bi-directional data bus.				
9	D3	8-bit bi-directional data bus.				
10	D4	8-bit bi-directional data bus.				
11	D5	8-bit bi-directional data bus.				
12	D6	8-bit bi-directional data bus.				
13	D7	8-bit bi-directional data bus.				
14	VDD	Power supply. (+3.0V)				
15	VSS	System ground. (0V)				
16	NC	Not connection. (Must be open)				
17	NC	Not connection. (Must be open)				
18	NC	Not connection. (Must be open)				
19	V0	LCD driving voltage for commons at negative frame.				
20	XV0	LCD driving voltage for commons at positive frame.				
21	NC	Not connection. (Must be open)				
22	NC	Not connection. (Must be open)				
23	NC	Not connection. (Must be open)				
24	NC	Not connection. (Must be open)				
25	VM	LCD driving voltage for commons.				



Pin No.	Symbol		Function					
26	NC	Not cor	nnectio	n. (Must be open)				
27	NC	Not cor	nnectio	n. (Must be open)				
28	NC	Not cor	nnectio	n. (Must be open)				
29	VG	LCD dr	iving vo	oltage for segments.				
30	NC	Not cor	Not connection. (Must be open)					
24	000	Select	Select the MPU system interface mode.					
31	686	P/S	C86	Interface				
		1	1	Parallel 68000 Series MPU Interface				
32	P/S	1	0	Parallel 8080 Series MPU Interface				
32 170	170	0	Х	Serial 4-Line SPI Interface				
33	NC	Not cor	Not connection. (Must be open)					
34	NC	Not cor	nnectio	n. (Must be open)				



# 2.3 Timing Characteristic



VDD = 3.3V, Ta = 25 °C

Item	Signal	Symbol	Condition	Min.	Max.	Unit
Address setup time	۵0	tAW6		0	_	
Address hold time	70	tAH6		10	_	
System cycle time		tCYC6		240	_	
Enable L pulse width (WRITE)		tEWLW		80	_	
Enable H pulse width (WRITE)	/RD	tEWHW		80	—	
Enable L pulse width (READ)		tEWLR		80	_	ns
Enable H pulse width (READ)		tEWHR		140		
Write data setup time		tDS6		40	_	
Write data hold time	07-00	tDH6		10	_	
Read data access time		tACC6	CL = 16 pF	_	70	
Read data output disable time		tOH6	CL = 16 pF	5	50	



VDD = 2.8V, Ta = 25 °C

ltem	Signal	Symbol	Condition	Min.	Max.	Unit
Address setup time	40	tAW6		0	_	
Address hold time	AU	tAH6		0	_	
System cycle time		tCYC6		400	_	
Enable L pulse width (WRITE)		tEWLW		220	_	
Enable H pulse width (WRITE)	/RD	tEWHW		180	_	
Enable L pulse width (READ)		tEWLR		220	_	ns
Enable H pulse width (READ)		tEWHR		180	_	
Write data setup time		tDS6		40	_	
Write data hold time	07-00	tDH6		20	_	
Read data access time		tACC6	CL = 16 pF	—	140	
Read data output disable time		tOH6	CL = 16 pF	10	100	

- Note 1. The input signal rise time and fall time (tr, tf) is specified at 15 ns or less. When the system cycle time is extremely fast, (tr + tf) ≤ (tCYC6 tEWLW tEWHW) for (tr + tf) ≤ (tCYC6 tEWLR tEWHR) are specified.
- Note 2. All timing is specified using 20% and 80% of VDD1 as the reference.
- Note 3. tEWLW and tEWLR are specified as the overlap between CSB being "L" and E.



System Bus Timing For 8080 Series MPU



VDD = 3.3V,	Ta =	25	°C
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Item	Signal	Symbol	Condition	Min.	Max.	Unit
Address setup time	40	tAW8		0	—	
Address hold time	AU	tAH8		10	—	
System cycle time		tCYC8		240	—	
Enable L pulse width (WRITE)	/WR	tCCLW		80	—	
Enable H pulse width (WRITE)		tCCHW		80	—	
Enable L pulse width (READ)		tCCLR		140	—	ns
Enable H pulse width (READ)		tCCHR		80		
WRITE Data setup time		tDS8		40	—	
WRITE Data hold time		tDH8		20	_	
READ access time		tACC8	CL = 16 pF	_	70	
READ Output disable time		tOH8	CL = 16 pF	5	50	



VDD = 2.8V, Ta = 25 °C

ltem	Signal	Symbol	Condition	Min.	Max.	Unit
Address setup time	40	tAW8		0		
Address hold time	A0	tAH8		0	-	1
System cycle time		tCYC8		400	-	1
/WR L pulse width (WRITE)	/WR	tCCLW		220		1
/WR H pulse width (WRITE)		tCCHW		180		1
/RD L pulse width (READ)	PD	tCCLR		220		ns
/RD H pulse width (READ)	RU	tCCHR		180	-	1
WRITE Data setup time		tDS8		40		1
WRITE Data hold time	D(7:0)	tDH8		20		1
READ access time	D[7:0]	tACC8	CL = 16 pF		140	1
READ Output disable time		tOH8	CL = 16 pF	10	100	1

- Note 1. The input signal rise time and fall time (tr, tf) is specified at 15 ns or less. When the system cycle time is extremely fast, (tr + tf) ≤ (tCYC8 tCCLW tCCHW) for (tr + tf) ≤ (tCYC8 tCCLR tCCHR) are specified.
- Note 2. All timing is specified using 20% and 80% of VDD1 as the reference.
- Note 3. tCCLW and tCCLR are specified as the overlap between CSB being "L" and WR and RD being at the "L" level.



# System Bus Timing For 4-Line Serial Interface





#### VDD = 3.3V, Ta = 25 °C

100 0.	ov, iu	
Min.	Max.	Unit
50		
25	_	]
25		
20	_	]
10	_	ns
20		]
10	_	]
20	_	]
40	_	]
	Min.    50    25    25    20    10    20    10    20    40	Min.  Max.    50     25     25     20     10     20     20     20     20     20     20     40

				VDD = 2.	8V, Ta =	25 °C
ltem	Signal	Symbol	Condition	Min.	Max.	Unit
Serial clock period		tSCYC		100	—	
SCLK "H" pulse width	SCLK	tSHW		50	_	
SCLK "L" pulse width		tSLW		50	_	
Address setup time	40	tSAS		30	_	
Address hold time	AU	tSAH		20	_	ns
Data setup time	804	tSDS		30	_	
Data hold time	SDA	tSDH		20	_	
CSB-SCLK time	CER	tCSS		30	_	
CSB-SCLK time	CSD	tCSH		60	—	

Note 1. The input signal rise and fall time (tr, tf) are specified at 15 ns or less. Note 2. All timing is specified using 20% and 80% of VDD as the standard.



# **Reset Timing**



### VDD = 3.3V, Ta = 25 °C

ltem	Symbol	Condition	Min.	Max.	Unit
Reset time	tR		_	1.0	
Reset "L" pulse width	tRW		1.0	_	us

#### VDD = 2.8V, Ta = 25 °C

ltem	Symbol	Condition	Min.	Max.	Unit
Reset time	tR		_	2.0	116
Reset "L" pulse width	tRW		2.0	_	us



# **3. QUALITY ASSURANCE SYSTEM**

# 3.1 Quality Assurance Flow Chart











### **3.2. Inspection Specification**

◆Scope : The document shall be applied to LCD Module for Monotype and Color STN(Ver, B01).

igoplusInspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level  $I\!I$  .

◆Equipment : Gauge 、 MIL-STD 、 Sample

◆Defect Level : Major Defect AQL : 0.4 ; Minor Defect : AQL : 1.5.

OUT Going Defect Level : Sampling .

Manner of appearance test :

- (1). The test be under 20W×2 fluorescent light ' and distance of view must be at 30 cm.
- (2). Standard of inspection : (Unit : mm)
- (3). The test direction is base on about around 45° of vertical line. (Fig. 1)
- (4). Definition of area . (Fig. 2)





A area : viewing area

#### Specification:

NO	Item	Criterion	Level
		1. 1 The part number is inconsistent with work order of Production.	Major
01	Product condition	1. 2 Mixed production types.	Major
		1.3 Assembled in inverse direction.	Major
02	Quantity	2. 1 The quantity is inconsistent with work order of production.	Major
03	Outline dimension	3.1 Product dimension and structure must conform to Structure diagram.	Major
		4. 1 Missing line character and icon.	Major
		4. 2 No function or no display.	Major
04	Electrical Testing	4. 3 Output data is error.	Major
		4, 4 LCD viewing angle defect.	Major
		4.5 Current consumption exceeds product specifications.	Major



n nm.
n nm.
1
Minor
•
<u> </u>
Minor

Total quantity

4



# Specification For Monotype and Color STN : (Ver.B01) NO Criterion Item Level Symbols : X : The length of crack Y: The width of crack. Z : The thickness of crack W : terminal length t : The thickness of glass a : LCD side length \_\_\_\_\_ 7.1 General glass chip: 7.1.1 Chip on panel surface and crack between panels: SF The crack of 07 Minor glass [NG] [OK] Seal width х Y z Crack can't enter ≦1/2 t ≦ a viewing area Crack can't exceed the $1/2 t < Z \leq 2 t$ ≦ a half of SP width.



#### ◆Specification For Monotype and Color STN:

(Ver.B01)

NO	Item	Criterion			
		Symbols : X : The length of crack Y : The width of crack. Z : The thickness of crack W : terminal length t : The thickness of glass a : LCD side length 7. 1. 2 Corner crack :			
		X Y Z			
07	The crack of	$ \leq 1/5 \text{ a}  \begin{array}{c} \text{Crack can't exceed the} \\ \text{half of SP width.} \end{array}  1/2 \text{ t} < \text{Z}  \leq 2 \text{ t} \end{array} $			
	glass	7.2 Protrusion over terminal : 7.2.1 Chip on electrode pad : X   Y   Z W   Y W   Y W   Y W   Y W   Y W   Y X   Y   Z Front $\leq a   \leq 1/2   W   \leq t$ Back Neglect	MINOF		







Specification For Monotype and Color STN: (Ver. B01)							
NO	Item	Criterion					
08	Backlight elements	8. 1 Backlight can't work normally.	Major				
		8, 2 Backlight doesn't light or color is wrong.	Major				
		8. 3 Illumination source flickers when lit.	Major				
09	General appearance	9. 1 Pin type must match type in specification sheet.	Major				
		9. 2 No short circuits in components on PCB or FPC.	Major				
		9. 3 Product packaging must the same as specified on packaging specification sheet.	Minor				
		9. 4 The folding and peeled off in polarizer are not acceptable.	Minor				
		9. 5 The PCB or FPC between B/L assembled distance (PCB or FPC) is $\leq 1.5$ mm.	Minor				



# 4. RELIABILITY TEST

# 4.1 Reliability Test Condition

(Ver.B01)

NO.	TEST ITEM	TEST CONDITION					
1	High Temperature	Keep in +80 ±2℃ 96 hrs					
-	Storage Test	Surrounding temperature, then storage at normal condition 4hrs.					
2	Low Temperature	Keep in -30 ±2°C 96 hrs					
	Storage Test	Surrounding temperature, then storage at normal condition 4hrs.					
	High Temperature /	Keep in +60 °C / 90% R.H duration for 96 hrs					
3	High Humidity	Surrounding temperature, then storage at normal condition 4hrs.					
	Storage Test	(Excluding the polarizer)					
4		$-30^{\circ}C \rightarrow +25^{\circ}C \rightarrow +80^{\circ}C \rightarrow +25^{\circ}C$					
	<b>Temperature Cycling</b>		(30mins)	(5mins)	(30mins)	(5mins)	
	Storage Test	10 Cycle					
		Surrounding temperature, then storage at normal condition 4hrs.					
5		Air Discharge:		Contact Discharge:			
		Apply 2 KV with 5 times			Apply 250 V with 5 times		
	ESD Test	Discharge for each polarity +/-			discharge for each polarity +/-		
		<b>1.</b> Temperature ambiance : $15^{\circ}$ C ~ $35^{\circ}$ C					
		2. Humidity relative : $30\% \sim 60\%$					
		3. Energy Storage Capacitance(Cs+Cd) : 150pF±10%					
		4. Discharge Resistance(Rd) : $330 \Omega \pm 10\%$					
		5. Discharge, mode of operation :					
		Single Discharge (time between successive discharges at least 1 sec)					
		(1 olerance if the output voltage indication : ±5%)					
6	Vibration Test	1. Sine wave $10 \sim 55$ Hz frequency (1 min/sweep)					
	(Packaged)	2. The amplitude of vibration :1.5 mm					
	· · · · · · · · · · · · · · · · · · ·	<b>3.</b> Each direction $(X \cdot Y \cdot Z)$ duration for 2 Hrs					
7			Packing V	Weight (Kg)	Drop Hei	ight (cm)	
			0	~ 45.4	12	22	
	Drop Test		45.4	~ 90.8	7	6	
	(Packaged)		90.8	~ 454	6	1	
			0ve	er 454	4	6	
		Drop Direction : ※1 corner / 3 edges / 6 sides each 1time					



# 5. PRECAUTION RELATING PRODUCT HANDLING

# 5.1 SAFETY

- 5.1.1 If the LCD panel breaks , be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes , please wash it off immediately by using soap and water.

# 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module , be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So , please handle it very carefully, do not touch , push or rub the exposed polarizing with anything harder than an HB pencil lead (glass , tweezers , etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth , as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands , this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is  $320 \pm 10^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM

## 5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}C \pm 5^{\circ}C$ and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush , shake , or jolt the module.

## **5.4 TERMS OF WARRANTY**

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

### 5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required. and where extremely high levels of reliability are required.



